Title: COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

Assignee: Intel Corporation

IN THE CLAIMS

Please amend the claims as follows:

- 1. (Original) An apparatus comprising:
- an embossing tool substrate made of a first metal, a first major surface of the substrate having an embossing profile;
- a first coating over the first major surface of the substrate, the first coating providing an adherable surface; and
- a second coating over the first coating, the second coating providing a non-adhesive outer surface.
- 2. (Currently amended) The apparatus of claim 1, wherein the first coating further comprises:
 - a layer of a second metal deposited over the embossing tool substrate;
 - a layer of metal oxide deposited over the layer of the second metal; and
 - a layer of metal nitride deposited over the layer of metal nitride.
- 3. (Original) The apparatus of claim 1, wherein the first coating further comprises:
 - a layer of zirconium deposited over the embossing tool substrate;
 - a layer of zirconium oxide deposited over the layer of zirconium; and
 - a layer of zirconium nitride deposited over the layer of zirconium oxide.
- 4. (Original) The apparatus of claim 1, wherein the second coating comprises poly-paraxylylene.
- 5. (Original) The apparatus of claim 3, wherein the zirconium layer is about 0.5 microns thick, the zirconium oxide layer is about 0.5 microns thick, the zirconium nitride layer is about 0.5 microns thick, and the second coating comprises poly-para-xylylene and is between about 2 microns and about 9 microns thick.

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

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6. (Original) The apparatus of claim 5, wherein the zirconium layer is 0.5 microns thick, the zirconium oxide layer is 0.5 microns thick, the zirconium nitride layer is 0.5 microns thick, and the second coating is between 2 microns and 9 microns thick.

- 7. (Canceled).
- 8. (Original) The apparatus of claim 2, wherein the second coating comprises poly-para-xylylene.
- 9-10. (Canceled).
- 11. (Original) The apparatus of claim 1, further comprising:
 - a heater apparatus to provide heat during an embossing operation; and
 - a pressure apparatus to apply pressure during the embossing operation.
- 12. (Original) The apparatus of claim 1, wherein the first coating further comprises a layer of zirconium deposited over the embossing tool substrate, and wherein the second coating comprises zirconium nitride deposited over the layer of zirconium.
- 13. 22. (Canceled)
- 23. (Original) An apparatus comprising:

an embossing tool that includes:

a tool substrate base; and

means attached to the tool substrate base for providing a hardened embossing surface with reduced adherence properties to an embossable substrate.

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24. (Original) The apparatus of claim 23, further comprising:

means for providing an embossable surface including a polymer film having attached thereto means for releasing the embossing tool, mixed with an epoxy resin.

- 25. (Original) The apparatus of claim 23, wherein the means for providing a hardened embossing surface with reduced adherence properties includes a layer of zirconium on the tool substrate base and a layer of zirconium nitride on the layer of zirconium.
- 26. (Original) The apparatus of claim 25, wherein the means for providing a hardened embossing surface with reduced adherence properties further includes a layer of zirconium oxide on the layer of zirconium nitride, and a layer of poly-para-xylylene on the layer of zirconium oxide.